



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-23
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ACE1*W6BAARU	A	CA2A	2016-09-23
Amount	UoM	Unit type	ST ECOPACK Grade	
1.60	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Nickel (Ni)		

Package Designator	Size	Nbr of instances	Shape	
CHP	1 - 1.45 - 0.6	6	No lead	
Comment	Package: UFDFPN 1X1.45X0.6 6L P0.5, MD valid for CP: SR1UARU, STM6519AUARUB6F.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ACE1*W6BAARU					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.241	mg	supplier	die	Silicon (Si)	7440-21-3		0.228	mg	946058	142500
die (s)				supplier	metallization	Aluminum (Al)	7429-90-5		0.002	mg	8299	1250
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	4149	625
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	4149	625
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.006	mg	24896	3750
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.002	mg	8299	1250
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.001	mg	4149	625
Leadframe	Copper & its alloys	0.036	mg	supplier	alloy	Nickel (Ni)	7440-02-0		0.033	mg	916667	20625
Leadframe				supplier	alloy	Palladium (Pd)	7440-05-3		0.002	mg	55556	1250
Leadframe				supplier	tape	Gold (Au)	7440-57-5		0.001	mg	27778	625
Die attach	Other organic materials	0.173	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.151	mg	872832	94375
Die attach				supplier	glue or tape	Amine Polymer	28630-26-4		0.014	mg	80925	8750
Die attach				supplier	glue or tape	aniline	67784-74-1		0.002	mg	11561	1250
Die attach				supplier	glue or tape	epoxy resin	25068-38-6		0.005	mg	28902	3125
Die attach				supplier	glue or tape	Epoxy resin molecular weight <= 700	Proprietary		0.001	mg	5780	625
Bonding wire	Other inorganic materials	0.048	mg	supplier	wire	Gold (Au)	7440-57-5		0.048	mg	1000000	30000
encapsulation	Other organic materials	1.102	mg	supplier	mold compound	Silica, vitreous	60676-86-0		0.881	mg	799456	550625
encapsulation				supplier	mold compound	Silica	7631-86-9		0.11	mg	99819	68750
encapsulation				supplier	mold compound	Epoxy Resin	25068-38-6		0.044	mg	39927	27500
encapsulation				supplier	mold compound	Epoxyde Bisphenol A Resin	Proprietary		0.022	mg	19964	13750
encapsulation				supplier	mold compound	Phenol Resin	29690-82-2		0.039	mg	35390	24375
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.006	mg	5445	3750